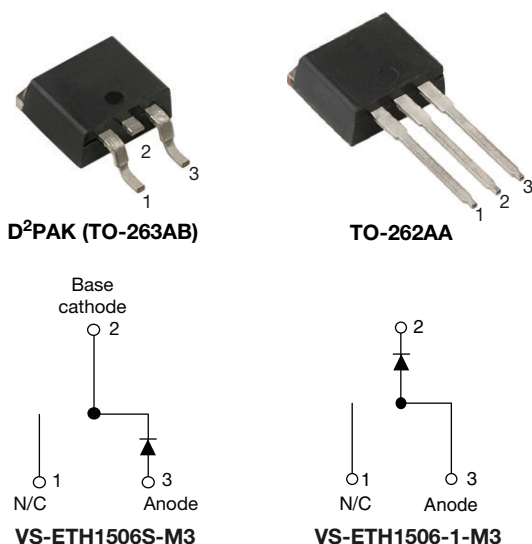


## Hyperfast Rectifier, 15 A FRED Pt®



### FEATURES

- Hyperfast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- AEC-Q101 qualified, meets JESD 201 class 1A whisker test
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



### DESCRIPTION / APPLICATIONS

Hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC Boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

### PRIMARY CHARACTERISTICS

$I_{F(AV)}$	15 A
$V_R$	600 V
$V_F$ at $I_F$	1.25 V
$t_{rr}$ (typ.)	21 ns
$T_J$ max.	175 °C
Package	D <sup>2</sup> PAK (TO-263AB), TO-262AA
Circuit configuration	Single

### ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Repetitive peak reverse voltage	$V_{RRM}$		600	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 139\text{ °C}$	15	A
Non-repetitive peak surge current	$I_{FSM}$	$T_C = 25\text{ °C}$	160	
Operating junction and storage temperatures	$T_J, T_{Stg}$		-65 to +175	°C

### ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ °C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}, V_R$	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
Forward voltage	$V_F$	$I_F = 15\text{ A}$	-	1.8	2.45	
		$I_F = 15\text{ A}, T_J = 150\text{ °C}$	-	1.25	1.6	
Reverse leakage current	$I_R$	$V_R = V_R$ rated	-	0.01	15	$\mu\text{A}$
		$T_J = 150\text{ °C}, V_R = V_R$ rated	-	20	200	
Junction capacitance	$C_T$	$V_R = 600\text{ V}$	-	12	-	pF
Series inductance	$L_S$	Measured lead to lead 5 mm from package body	-	8.0	-	nH

**DYNAMIC RECOVERY CHARACTERISTICS** ( $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1.0\text{ A}$ , $dI_F/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	21	26	ns
		$I_F = 1.5\text{ A}$ , $dI_F/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	25	36	
		$T_J = 25\text{ }^{\circ}\text{C}$	-	29	-	
		$T_J = 125\text{ }^{\circ}\text{C}$	-	65	-	
Peak recovery current	$I_{RRM}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	3.9	-	A
		$T_J = 125\text{ }^{\circ}\text{C}$	-	7.0	-	
Reverse recovery charge	$Q_{rr}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	60	-	nC
		$T_J = 125\text{ }^{\circ}\text{C}$	-	240	-	
Reverse recovery time	$t_{rr}$	$I_F = 15\text{ A}$ $dI_F/dt = 200\text{ A}/\mu\text{s}$ $V_R = 390\text{ V}$	-	42	-	ns
Peak recovery current	$I_{RRM}$		-	21	-	A
Reverse recovery charge	$Q_{rr}$		-	480	-	nC

**THERMAL - MECHANICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	$T_J$ , $T_{Stg}$		-65	-	175	$^{\circ}\text{C}$
Thermal resistance, junction to case	$R_{thJC}$		-	1.3	1.51	$^{\circ}\text{C}/\text{W}$
Thermal resistance, junction to ambient	$R_{thJA}$	Typical socket mount	-	-	70	
Thermal resistance, case to heatsink	$R_{thCS}$	Mounting surface, flat, smooth and greased	-	0.5	-	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style D <sup>2</sup> PAK (TO-263AB)	ETH1506SH			
		Case style TO-262AA	ETH1506-1H			

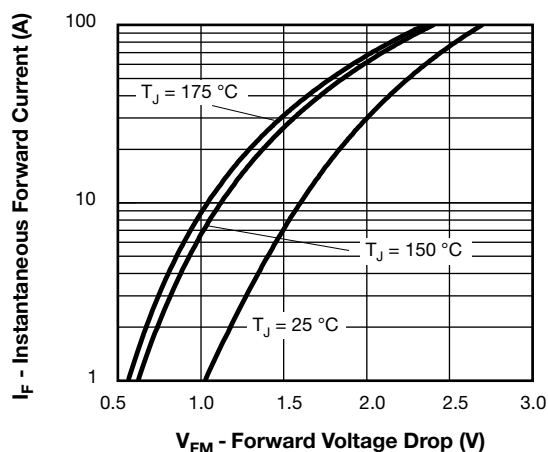


Fig. 1 - Typical Forward Voltage Drop Characteristics

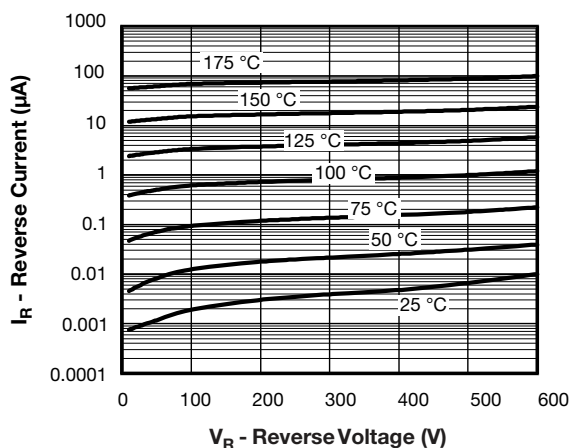


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

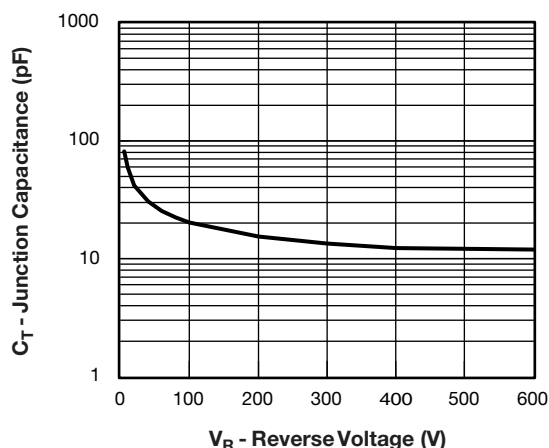


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

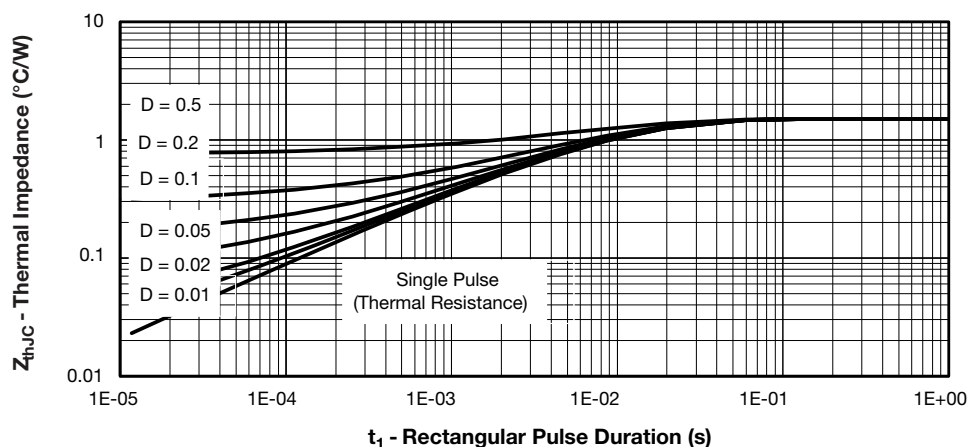
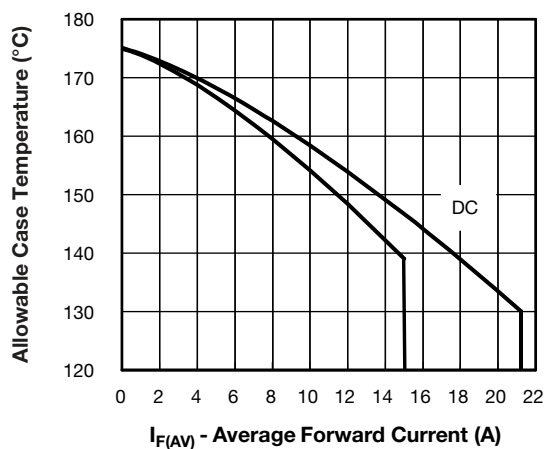

Fig. 4 - Max. Thermal Impedance  $Z_{thJC}$  Characteristics


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

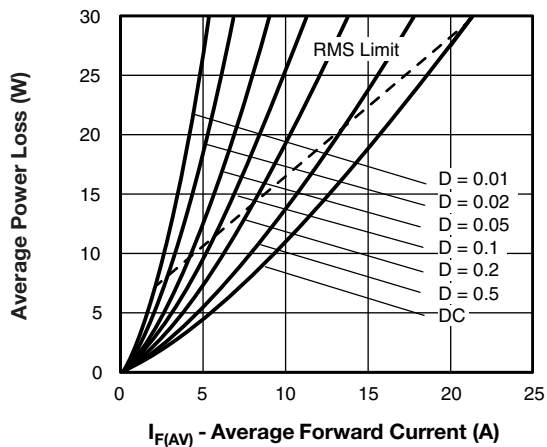


Fig. 6 - Forward Power Loss Characteristics

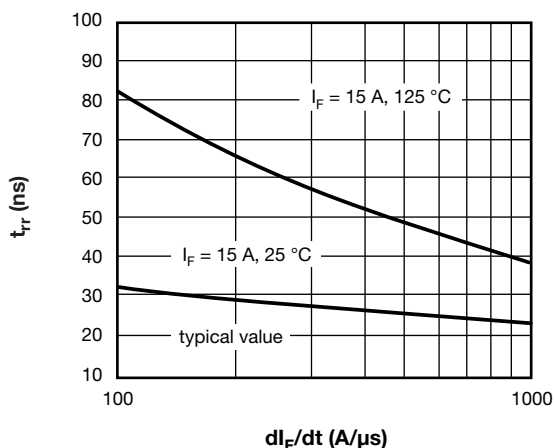
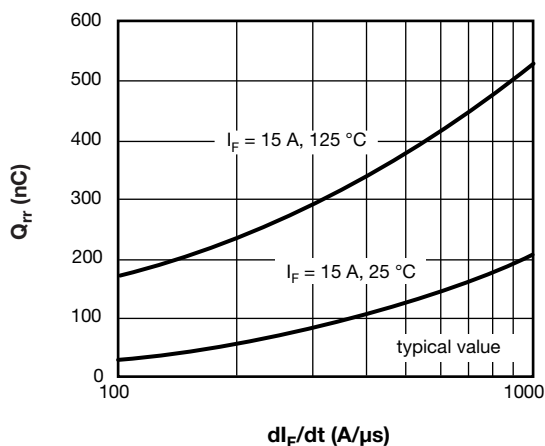
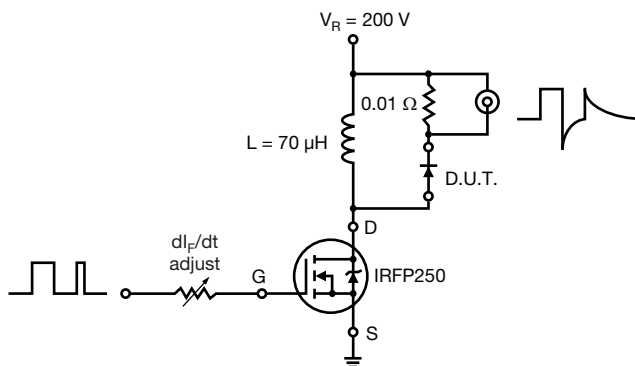

Fig. 7 - Typical Reverse Recovery Time vs.  $di_F/dt$ 

Fig. 8 - Typical Stored Charge vs.  $di_F/dt$ 


Fig. 9 - Reverse Recovery Parameter Test Circuit

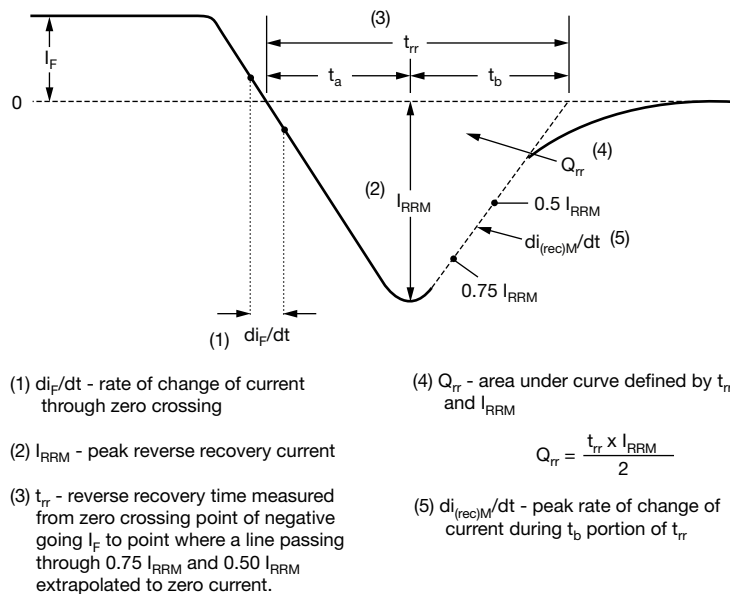


Fig. 10 - Reverse Recovery Waveform and Definitions

**ORDERING INFORMATION TABLE**

Device code	<b>VS-</b>	<b>E</b>	<b>T</b>	<b>H</b>	<b>15</b>	<b>06</b>	<b>S</b>	<b>TRL</b>	<b>H</b>	<b>M3</b>
	①	②	③	④	⑤	⑥	⑦	⑧	⑨	⑩
①	- Vishay Semiconductors product									
②	- Circuit configuration E = single diode									
③	- T = TO-220									
④	- H = Hyperfast recovery time									
⑤	- Current code (15 = 15 A)									
⑥	- Voltage code (06 = 600 V)									
⑦	- • S = D <sup>2</sup> PAK - • -1 = TO-262									
⑧	- • None = tube - • TRL = tape and reel (left oriented, for D <sup>2</sup> PAK package) - • TRR = tape and reel (right oriented, for D <sup>2</sup> PAK package)									
⑨	- H = AEC-Q101 qualified									
⑩	- Environmental digit: M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free									

**ORDERING INFORMATION (Example)**

PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-ETH1506SHM3	50	Antistatic plastic tube
VS-ETH1506-1HM3	50	Antistatic plastic tube
VS-ETH1506STRRHM3	800	13" diameter reel
VS-ETH1506STRLHM3	800	13" diameter reel

**LINKS TO RELATED DOCUMENTS**

Dimensions	D <sup>2</sup> PAK (TO-263AB)	<a href="http://www.vishay.com/doc?95046">www.vishay.com/doc?95046</a>
	TO-262AA	<a href="http://www.vishay.com/doc?95419">www.vishay.com/doc?95419</a>
Part marking information	D <sup>2</sup> PAK (TO-263AB)	<a href="http://www.vishay.com/doc?95444">www.vishay.com/doc?95444</a>
	TO-262AA	<a href="http://www.vishay.com/doc?95443">www.vishay.com/doc?95443</a>
Packaging information	D <sup>2</sup> PAK (TO-263AB)	<a href="http://www.vishay.com/doc?95032">www.vishay.com/doc?95032</a>



## D<sup>2</sup>PAK

### DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D<sup>2</sup>PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

#### Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB

### TO-262

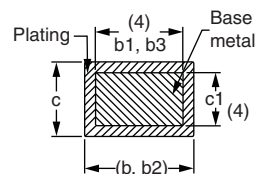
**DIMENSIONS** in millimeters and inches

Modified JEDEC® outline TO-262



#### Lead assignments

- Diodes**  
 1. - Anode (two die)/open (one die)  
 2., 4. - Cathode  
 3. - Anode



Section B - B and C - C  
Scale: None

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.36	3.71	0.132	0.146	

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline



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